



SOT1992-1(DD)

HLSON16, thermal enhanced low profile small outline; no leads, 16 terminals, 0.125 dimple wettable flank, 0.5 mm pitch, 4.5 mm x 3.5 mm x 1.45 mm body

27 March 2019

Package information

1 Package summary

Terminal position code	D (double)
Package type descriptive code	HLSON16
Package style descriptive code	HLSON (thermal enhanced low profile small outline; no leads)
Mounting method type	S (surface mount)
Issue date	12-02-2019
Manufacturer package code	98ASA01382D

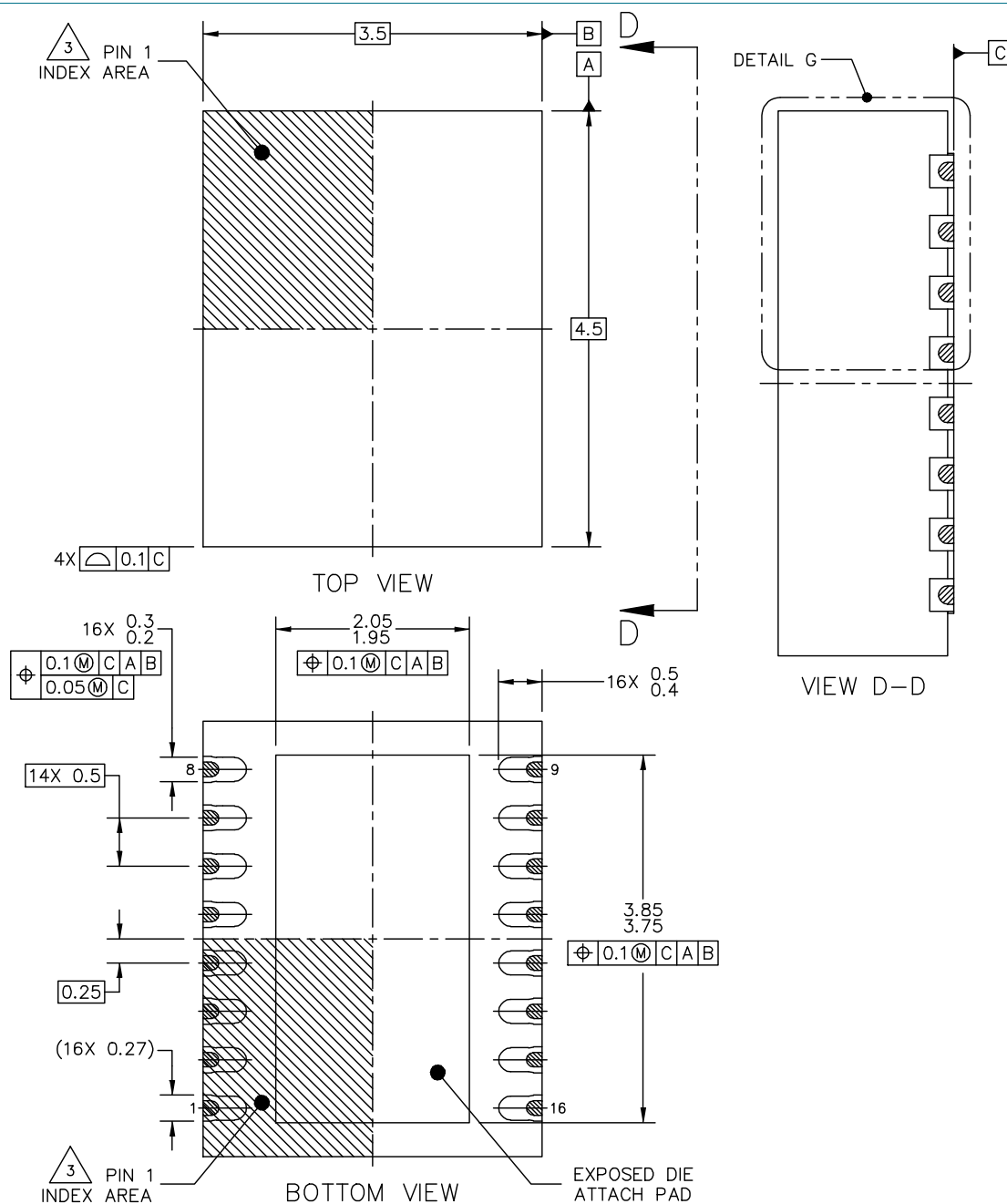
Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	-	4.5	-	mm
package width	-	3.5	-	mm
seated height	-	1.45	-	mm
nominal pitch	-	0.5	-	mm
actual quantity of termination	-	16	-	



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2 Package outline



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DATE: 12 FEB 2019

MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: NON JEDEC	DRAWING NUMBER: 98ASA01382D	REVISION: 0
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Figure 1. Package outline HLSON16 (SOT1992-1(DD))

HLSON16, thermal enhanced low profile small outline; no leads, 16 terminals, 0.125 dimple wettable flank, 0.5 mm pitch, 4.5 mm x 3.5 mm x 1.45 mm body

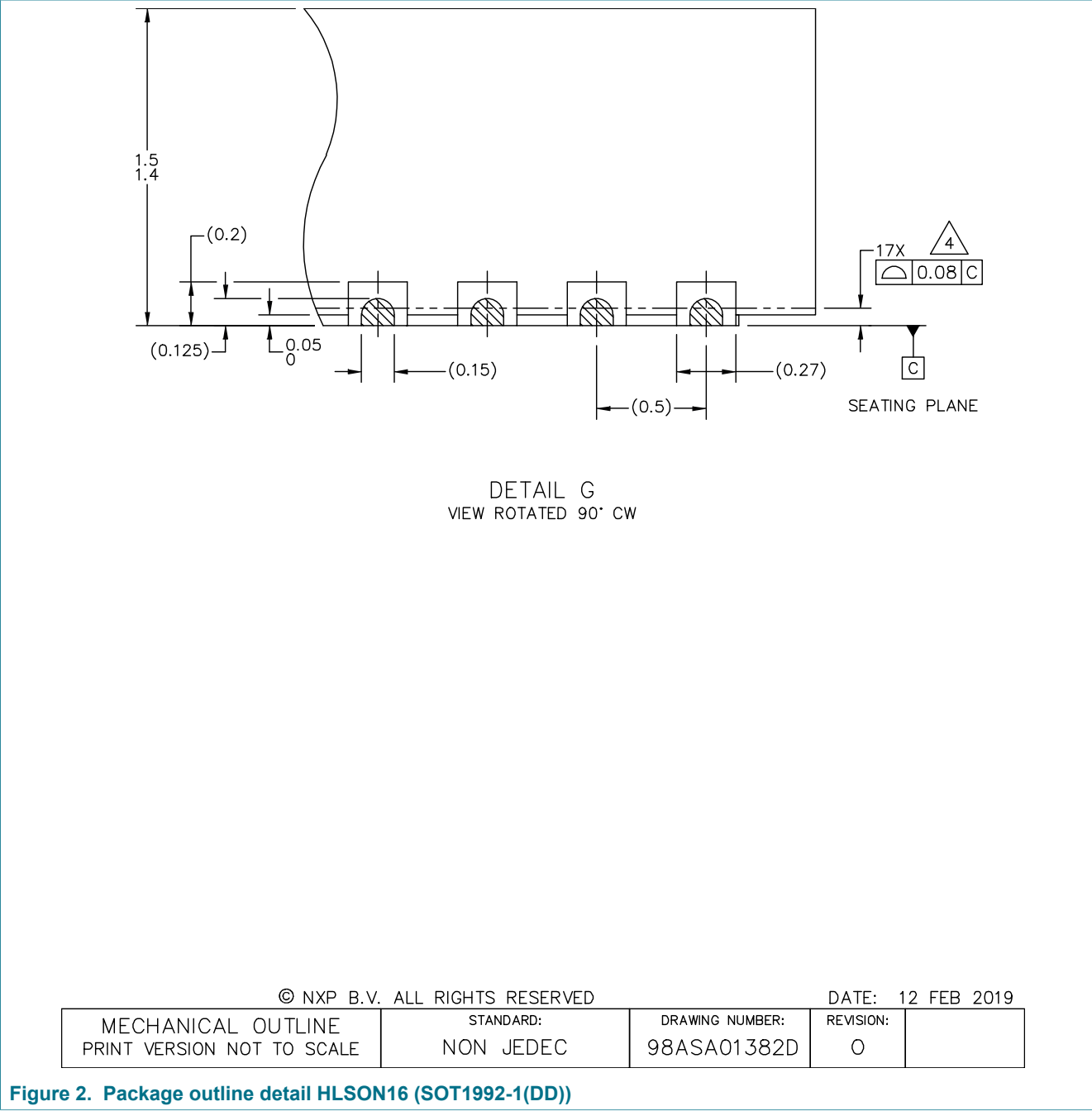


Figure 2. Package outline detail HLSON16 (SOT1992-1(DD))

HLSON16, thermal enhanced low profile small outline; no leads, 16 terminals, 0.125 dimple wettable flank, 0.5 mm pitch, 4.5 mm x 3.5 mm x 1.45 mm body

3 Soldering

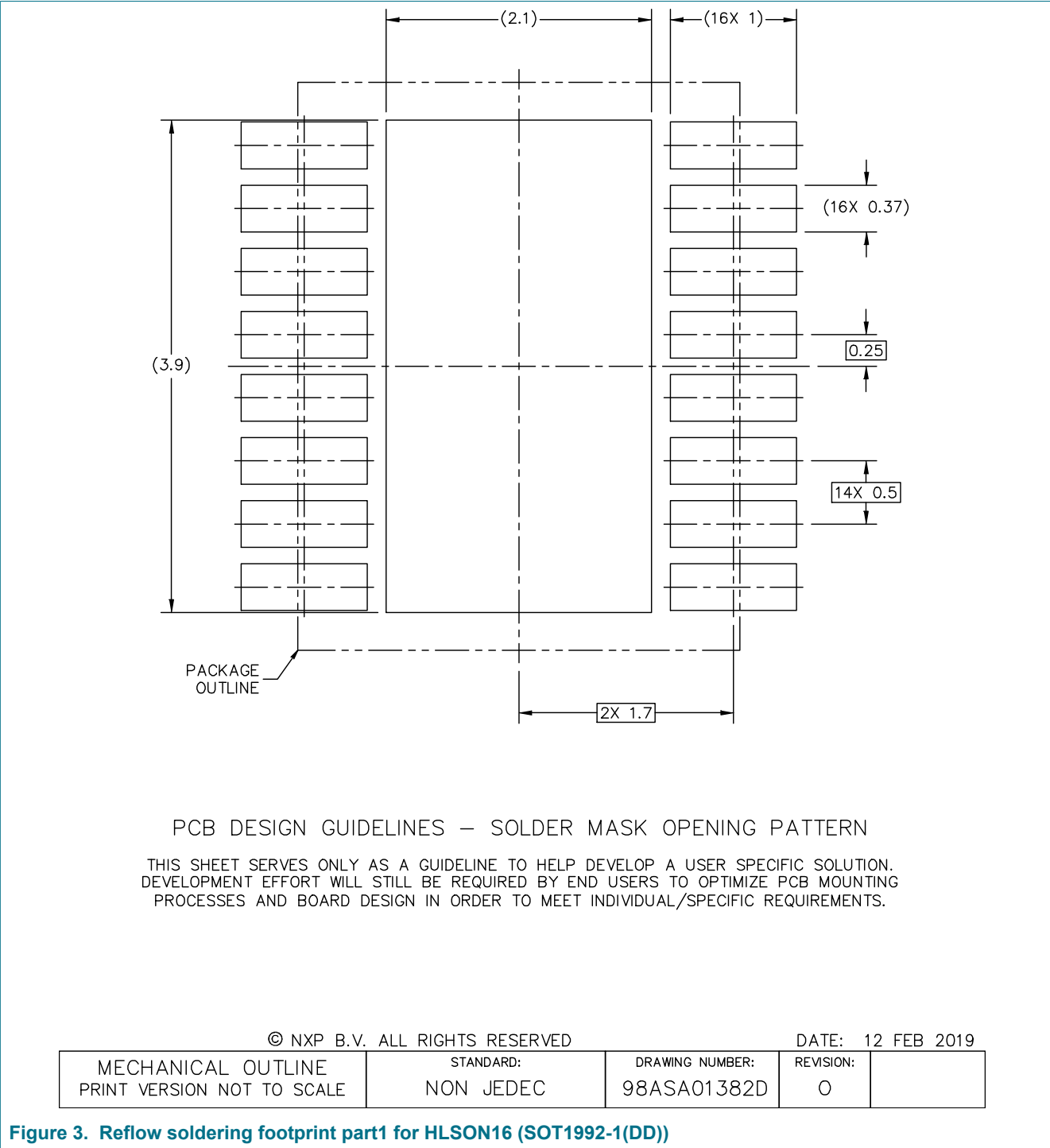


Figure 3. Reflow soldering footprint part1 for HLSON16 (SOT1992-1(DD))

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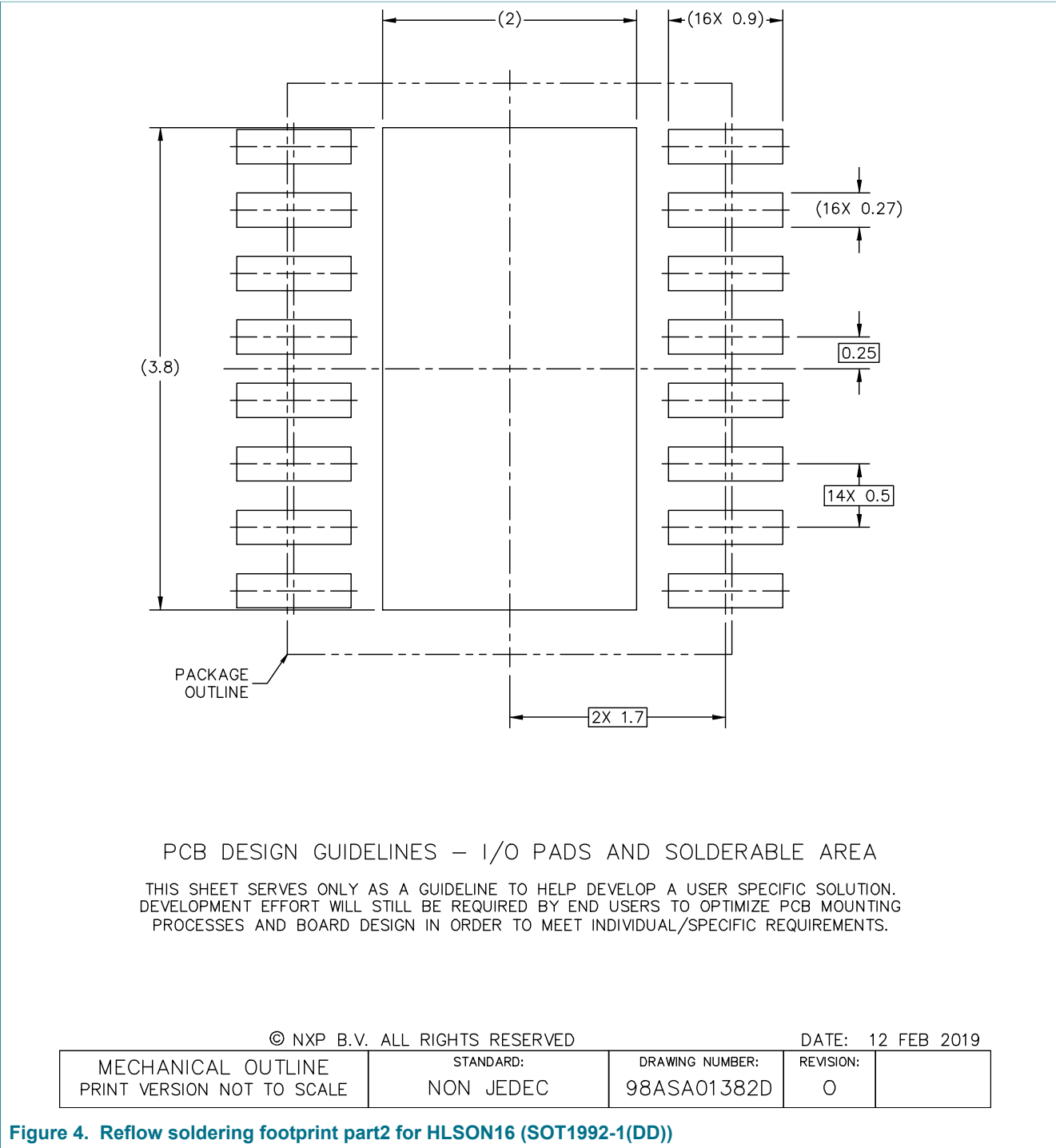
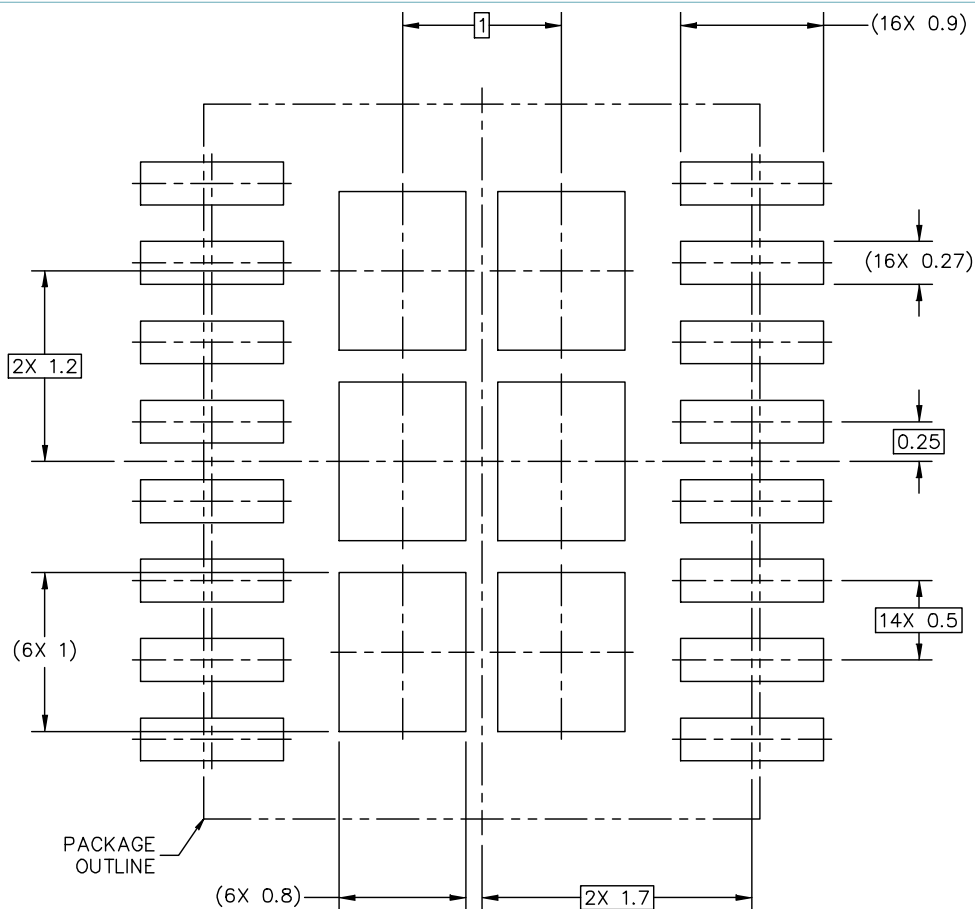


Figure 4. Reflow soldering footprint part2 for HLSON16 (SOT1992-1(DD))

HLSON16, thermal enhanced low profile small outline; no leads, 16 terminals, 0.125 dimple wettable flank, 0.5 mm pitch, 4.5 mm x 3.5 mm x 1.45 mm body



RECOMMENDED STENCIL THICKNESS 0.125

PCB DESIGN GUIDELINES – SOLDER PASTE STENCIL

THIS SHEET SERVES ONLY AS A GUIDELINE TO HELP DEVELOP A USER SPECIFIC SOLUTION.
DEVELOPMENT EFFORT WILL STILL BE REQUIRED BY END USERS TO OPTIMIZE PCB MOUNTING
PROCESSES AND BOARD DESIGN IN ORDER TO MEET INDIVIDUAL/SPECIFIC REQUIREMENTS.

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Figure 5. Reflow soldering footprint part3 for HLSON16 (SOT1992-1(DD))

HLSON16, thermal enhanced low profile small outline; no leads, 16 terminals, 0.125 dimple wettable flank, 0.5 mm pitch, 4.5 mm x 3.5 mm x 1.45 mm body

- NOTES:
- 1. ALL DIMENSIONS ARE IN MILLIMETERS.
 - 2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
 - 3. PIN 1 FEATURE SHAPE, SIZE AND LOCATION MAY VARY.
 - 4. COPLANARITY APPLIES TO LEADS.
 - 5. MIN. METAL GAP SHOULD BE 0.2 MM.

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Figure 6. Package outline note HLSON16 (SOT1992-1(DD))

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